

承認書

SPECIFICATION FOR APPROVAL

● 客戶名称	
● Customer	
● 客戶品號	
● Customer Part No.	
● 产品品號	HC-J2012CHMWGTP-F1
● Brightek Part No.	
● 产品規格描述	0807白翠绿双色
● Specification	
● 製錶人	王清
● Prepared By	
● 審核	李东平
● Checkedy	
● 客戶回簽	
● Customer	
● 送样日期:	
● Deliver date:	

說明：一、謹致執事者：茲提供敝公司產品之有關詳細規格及圖面資料，敬請給予辦理測試認定手續。

同時敬請 送返一份附有貴公司簽認之測試認定後之樣品認定書。

We are sending you our specification and drawings for your approval. Please return to us one

copy "For Approval" with your approved signatures.

二、客戶意見欄 Customer' S Proposal

☐ Approve 承認 (請於認可欄中簽名)

☐ Disagree 不同意

Reason 原因:

光宇集团 中高端光电元件定制企业，20多年封装经验，品质稳定，值得信赖，体现光的价
光宇集团国际（香港）有限公司

GTU Group International (HK) Co., Limited

广东光宇半导体科技有限公司

工厂地址：东莞市寮步镇松湖智谷 A2 栋 3 楼

东莞市弘呈光电有限公司

DongGuan Hong cheng Optoelectronics Co., Ltd.

工厂地址：广东省东莞市樟木头镇莞樟路樟木头段 15 号 15 栋 2108 号

ADD: Room 2108, No. 1 building, Wanhui Garden, East Guanzhang Road, Zhangmutou, Dongguan, Guangdong, China

TEL: 0769-87797616 87182291 Fax: 0769-82337396 www.hc-led168.com

业务联系人：李顺阳 13925714318 (微信同号) 销售总监 企业邮箱：sales@led-hc.com



版本/版次	修改日期	修改内容

Features

2.0mm × 1.7mm SMD LED, 0.8mm thickness

Low power consumption

Wide view angle

Package: 3000pcs/reel

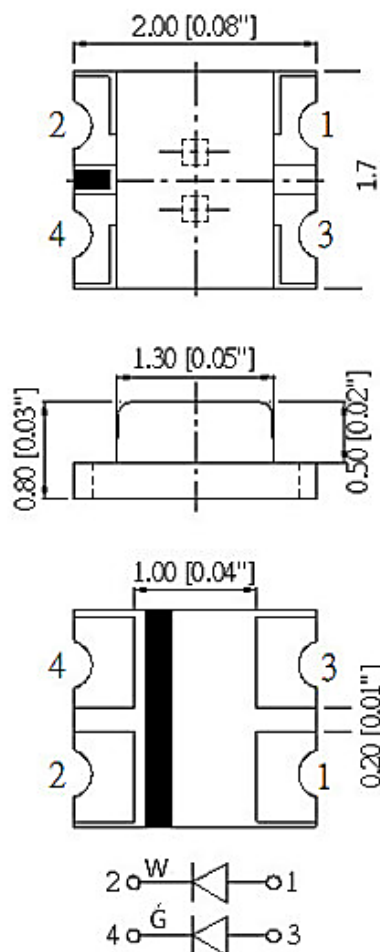
RoHS Compliant

Applications

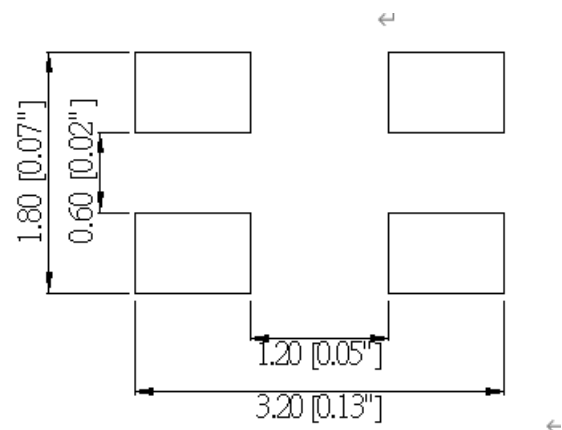
Ideal for back light and indicator

Various colors and lens types available

Package outlines



Recommend Pad Layout



Part No.	Emitted color	Dice	Lens color
HC-J2012CHMWGTP-F1	White	InGaN/GaN	Water transparent
	Green	InGaN/GaN	

Notes:

1. All dimensions are in millimeters (inches);
2. Tolerances are $\pm 0.1\text{mm}$ (0.004inch) unless otherwise noted.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Value		Unit
		G	W	
Power dissipation	Pd	72	72	mW
Forward current	If	20		mA
Reverse voltage	Vr	5		V
Operating temperature	Top	-40 ~+80		°C
Storage temperature	Tstg	-40 ~+85		°C
Peak pulsing current	Ifp	80		mA

Electro-Optical Characteristics (Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Dominant wavelength	If=5mA	λ_d W	10000	15000	--	K
		G	520	530	--	nm
Forward voltage	If=5mA	Vf W	2.5	--	3.0	V
		G	2.5	--	3.0	
Luminous intensity	If=5mA	Iv W	100	--	360	mcd
		G	100	--	300	
Viewing angle at 50% Iv	If=10mA	2 θ 1/2	--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	10	μ A

Optical Characteristic Curves (Green)

PURE GREEN

(25°C) Ambient Temperature Unless Otherwise Noted

Fig1. Forward Current vs. Forward Voltage

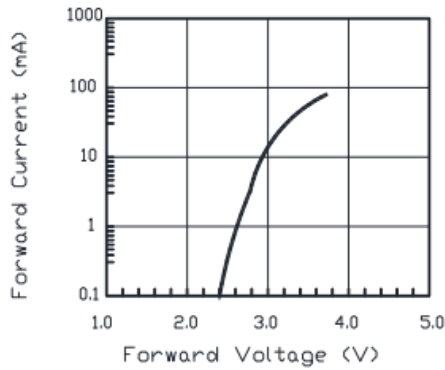


Fig2 Relative Luminous Intensity Vs Forward current

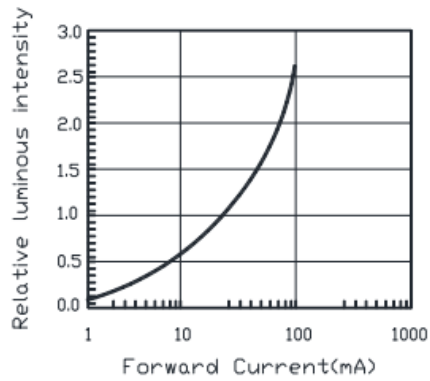


Fig3. Forward Current Derating Curve

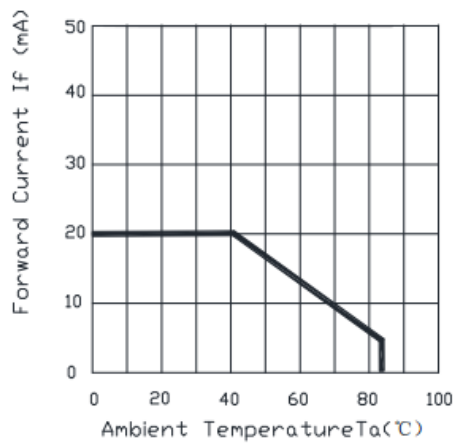


Fig4. Relative Luminous Intensity vs Ambient Temperature

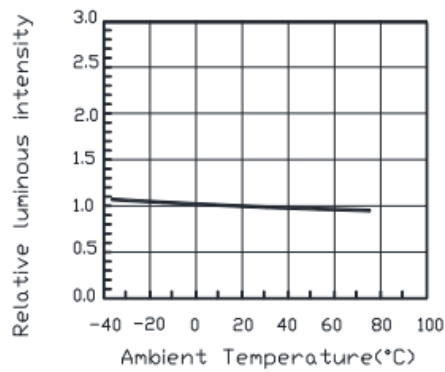


Fig5. Relative Intensity vs. Wavelength

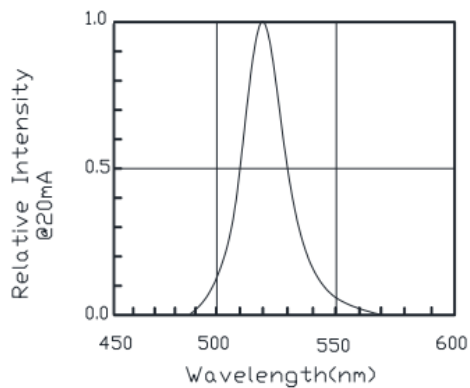
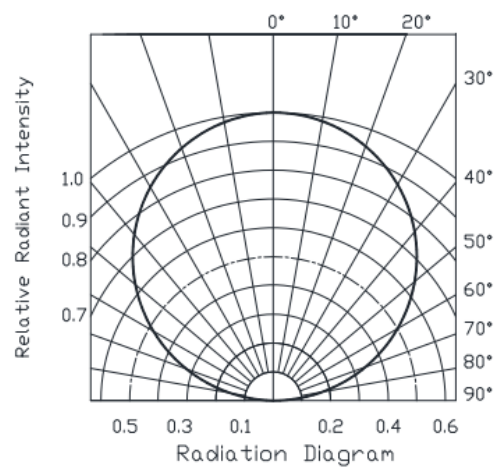


Fig6 Spatial Distribution



Optical Characteristic Curves (White)

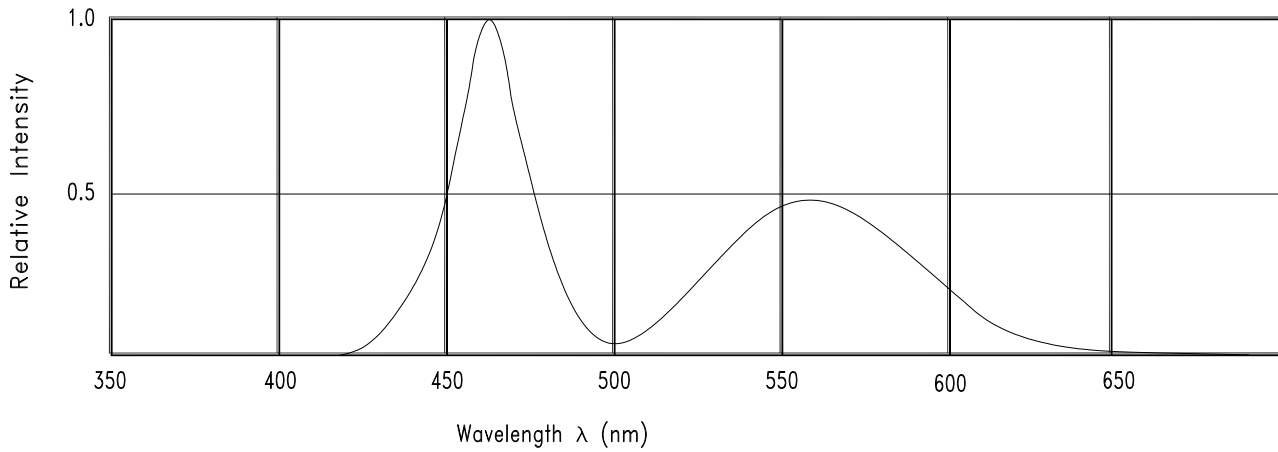


Fig.1 Relative Intensity vs. Wavelength

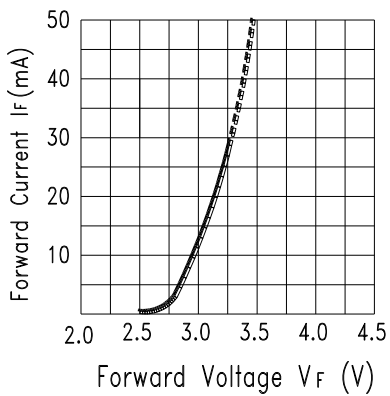


Fig.2 Forward Current vs. Forward Voltage

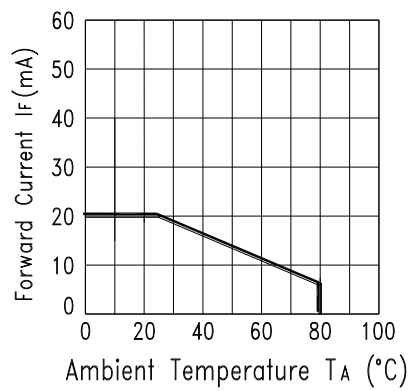


Fig.3 Forward Current Derating Curve

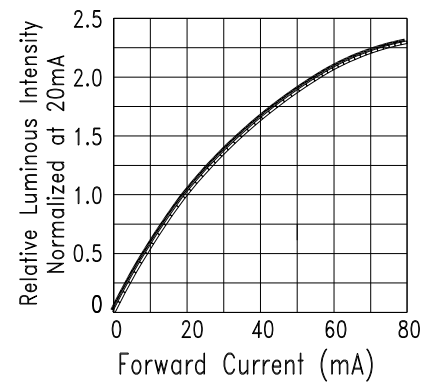


Fig.4 Relative Luminous Intensity vs. Forward Current

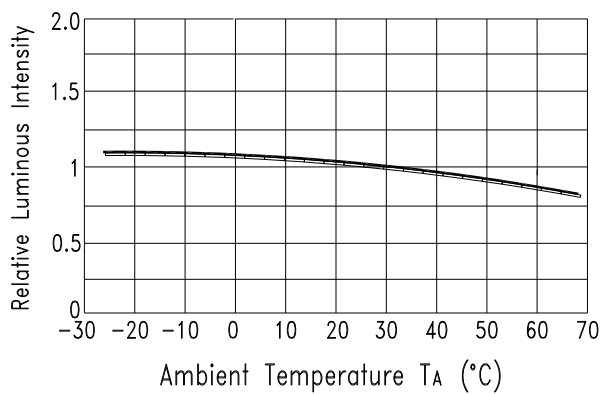


Fig.5 Luminous Intensity vs. Ambient Temperature

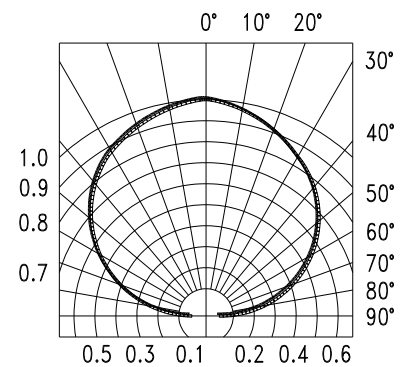
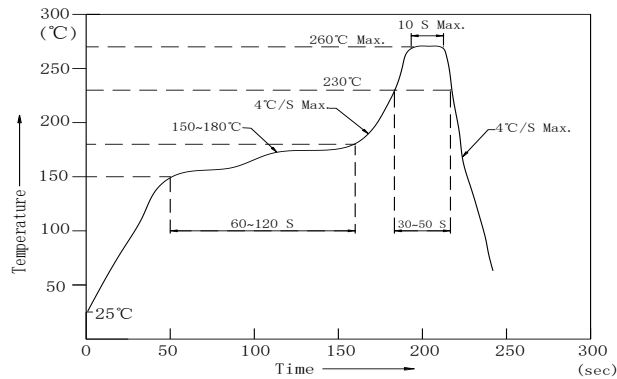


Fig.6 Spatial Distribution

Reflow Profile

■ Reflow Temp/Time



Notes:

1. We recommend the reflow temperature 245°C ($\pm 5^{\circ}\text{C}$).the maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

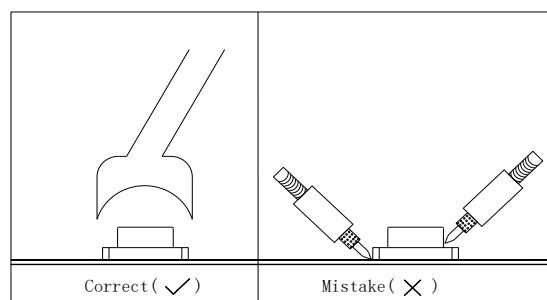
■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 320°C ($\pm 20^{\circ}\text{C}$). If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$).

Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 350°C .

■Rework

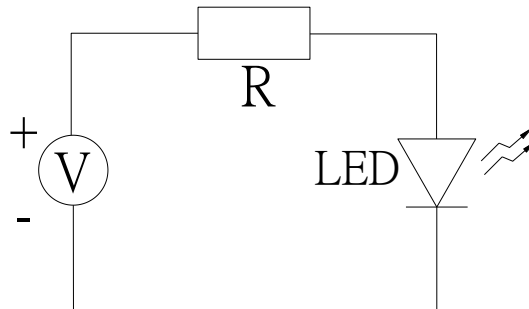
1. Customer must finish rework within 5 sec under 340°C .
2. The head of iron cannot touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature: 5°C~30°C

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. after the package is opened, the products should be used within a week or they should be keeping to stored at ≤ 20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

3.1 60±3°C x (12~24hrs) and <5%RH, taped reel type

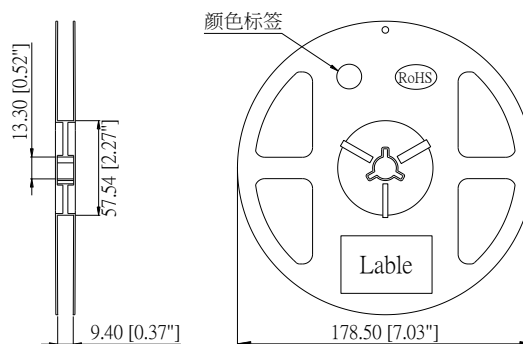
3.2 100±3°C x (45min~1hr), bulk type

3.3 130±3°C x (15~30min), bulk type

Test Items and Results of Reliability

Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Temperature Cycle	-40°C 30min ↑→(25°C/5min)↓ 100°C 30min	100 cycle	0/22
	Thermal Shock	Ta=-40°C 15min ↑↓ 100°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	Ta=100°C	1000 hrs	0/22
	Humidity Heat Storage	Ta=60°C RH=95%	1000 hrs	0/22
	Low Temperature Storage	Ta=-40°C	1000 hrs	0/22
Operation Sequence	Life Test	Ta=25°C IF=20mA	1000 hrs	0/22
	High Humidity Heat Life Test	Ta=60°C RH=95% IF=10mA	500 hrs	0/22
	Low Temperature Life Test	Ta=-20°C IF=20mA	1000 hrs	0/22

- **Feeding Direction**



Technical drawing of a mechanical part, showing top and side views with dimensions in millimeters (mm) and inches (in).

Top View Dimensions:

- Overall width: 8.00 [0.31"]
- Overall height: 5.25 [0.21"]
- Distance from left edge to first hole center: 2.00 [0.08"]
- Distance between hole centers: 4.00 [0.16"]
- Distance from right edge to last hole center: 1.75 [0.07"]
- Hole diameter: $\varnothing 1.50 [\varnothing 0.06"]$
- Distance from left edge to first square feature center: 4.00 [0.16"]
- Distance between square feature centers: 1.78 [0.07"]
- Distance from right edge to last square feature center: 1.78 [0.07"]

Side View Dimensions:

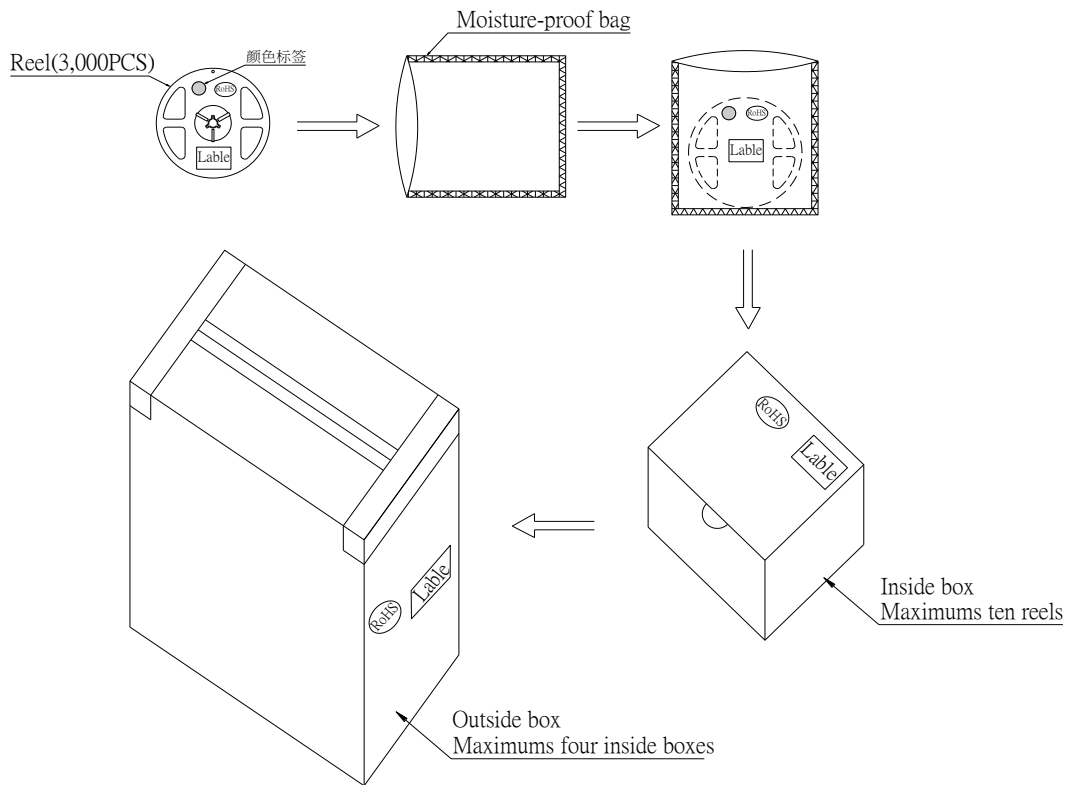
- Overall height: 0.93 [0.04"]
- Distance from top edge to first step: 0.23 [0.01"]
- Distance from top edge to second step: 1.00 [0.04"]

Section A-A: Indicated by arrows pointing to the top and bottom edges of the part.

Figure 1 illustrates the schematic diagram of the LED strip assembly process. The top part shows a plan view of the LED strip, divided into three main sections: 'Empty parts (Min.25pcs)', 'Loaded parts (LED:4000pcs)', and 'Empty parts (Min.75pcs)'. The bottom part shows a cross-sectional view of the strip, divided into 'Conclusion parts (Min.100mm)' and 'Introduction parts (Min.300mm)'. An arrow indicates the 'Feeding Direction' from right to left.

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
4. 4,000pcs/Reel.

2017 Series SMD Chip LED Lamps Packaging Specifications



Notes:

Reeled products (numbers of products are 3,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, ten moisture-proof bag of maximums (total maximum number of products are 30,000pcs) packed in an inside box (about size: 240x 220x 120mm) and four inside boxes of maximums are put in the outside box (about size: 460mm x 246mm x 250mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. and quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has it to three steps.